Product Change Notification - KMIO-21YLLS346

Date: 31 Aug 2017

Product Category: Interface- Serial Peripherals

Notification subject: CCB 2780 Final Notice: Qualification of CuPdAu bond wire and A194-FH lead frame material for selected products of the 160K wafer technology available in 24L QFN package at NSEB assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected products of the 160K wafer technology available in 24L QFN package at NSEB assembly site.

Pre Change:
Using gold (Au) bond wire and EFTEC-64T lead frame material.

Post Change:
Using palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	A194-FH

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
September 18, 2017 (1738)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2016				->	August 2017					September 2017			
Workweek	45	46	47	48		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date	X													
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation Date													X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
November 02, 2016: Issued initial notification.
August 18, 2017: Issued final notification. Attached qualification report. Provided estimated first ship date on September 18, 2017.
August 31, 2017: Re-issued final notification to update subject from Initial Notice to Final Notice.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KMIO-21YLLS346_Affected CPN.pdf
PCN_KMIO-21YLLS346_Qual Report.pdf
PCN_KMIO-21YLLS346_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Number (CPN)

PCN_KMIO-21YLLS346
CATALOG_PART_NBR
MCP23018-E/MJ
MCP23018T-E/MJ
MCP23S18-E/MJ
MCP23S18T-E/MJ